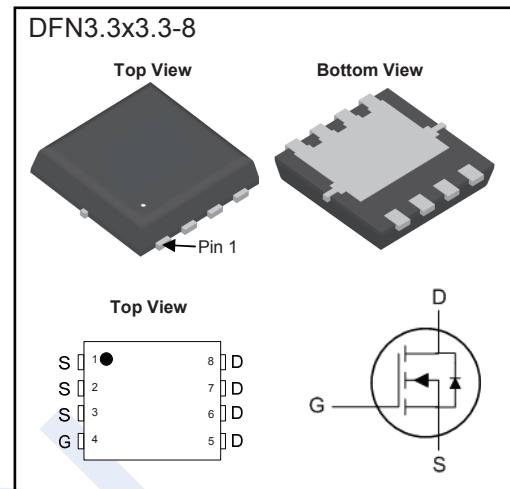


N-Channel MOSFET

KI30N03DFN

■ Features

- $V_{DS} (V) = 30 \text{ V}$
- $I_{D\text{MAX}} = 28 \text{ A}$
- $R_{DS(\text{ON})} (\text{at } V_{GS} = 10 \text{ V}) < 18 \text{ m}\Omega$

■ Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current, $V_{GS} @ 10\text{V}$ (Note 1)	I_D	28	A
		18	
		11.7	
		7.4	
		9.4	
		6	
	I_{DM}	56	
Pulsed Drain Current (Note 2)	I_{AS}	21	
Single Pulse Avalanche Energy (Note 3)	E_{AS}	72	mJ
Power Dissipation (Note 4)	P_D	20.8	W
		4.2	
		1.67	
Thermal Resistance.Junction- to-Ambient (Note 1)	R_{thJA}	75	°C/W
		30	
Thermal Resistance.Junction- to-Case (Note 1)	R_{thJC}	6	
Junction Temperature	T_J	150	°C
Storage Temperature Range	T_{stg}	-55 to 150	

N-Channel MOSFET

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■ Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D = 250 \mu\text{A}, V_{GS} = 0\text{V}$	30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA
		$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^\circ\text{C}$			5	
Gate to Source Leakage Current	I_{GS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Gate to Source Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	1.2		2.5	V
Static Drain-Source On-Resistance (Note 2)	$R_{DS(\text{ON})}$	$V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$			18	$\text{m}\Omega$
		$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$			30	
Forward Transconductance	g_{FS}	$V_{DS} = 5 \text{ V}, I_D = 30 \text{ A}$		19.4		S
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}, V_{DS} = 15 \text{ V}, f = 1 \text{ MHz}$		572	801	pF
Output Capacitance	C_{oss}			80	112	
Reverse Transfer Capacitance	C_{rss}			65	91	
Gate Resistance	R_g	$V_{GS} = 0 \text{ V}, V_{DS} = 0 \text{ V}, f = 1 \text{ MHz}$		2.5	5	Ω
Single Pulse Avalanche Energy (Note 5)	E_{AS}	$V_{DD}=25\text{V}, L=0.1\text{mH}, I_{AS}=10\text{A}$	16			mJ
Total Gate Charge	$Q_g(4.5\text{V})$	$V_{GS} = 4.5\text{V}, V_{DS} = 15 \text{ V}, I_D = 15 \text{ A}$		6.2	8.7	nC
Gate Source Charge	Q_{gs}			2.4	3.4	
Gate Drain Charge	Q_{gd}			2.5	3.5	
Turn-On DelayTime	$t_{d(on)}$	$V_{GS} = 10\text{V}, V_{DD} = 15 \text{ V}, R_G = 3.3 \Omega, I_D = 15\text{A}$		3	6	ns
Turn-On Rise Time	t_r			7.6	14	
Turn-Off DelayTime	$t_{d(off)}$			20.8	42	
Turn-Off Fall Time	t_f			4	8	
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 30 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$		17		nC
Body Diode Reverse Recovery Charge	Q_{rr}			3		
Maximum Body-Diode Continuous Current (Note 1,6)	I_S	$V_G=V_D=0\text{V}, \text{Force Current}$			28	A
Pulsed Source Current (Note 2,6)	I_{SM}				56	
Diode Forward Voltage (Note 2)	V_{SD}	$V_{GS} = 0 \text{ V}, I_S = 1 \text{ A}$			1.2	V

Notes:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD}=25\text{V},V_{GS}=10\text{V},L=0.1\text{mH},I_{AS}=21\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

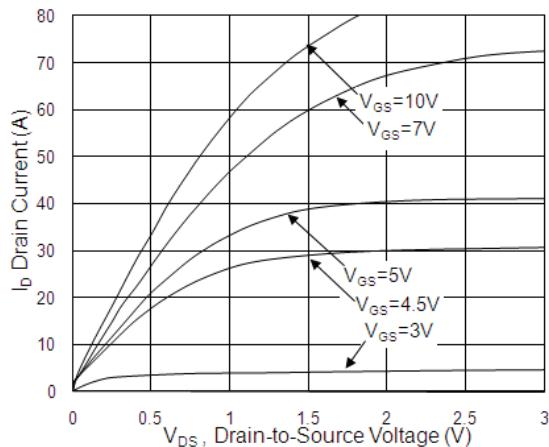
N-Channel MOSFET**KI30N03DFN****■ Typical Characteristics**

Fig.1 Typical Output Characteristics

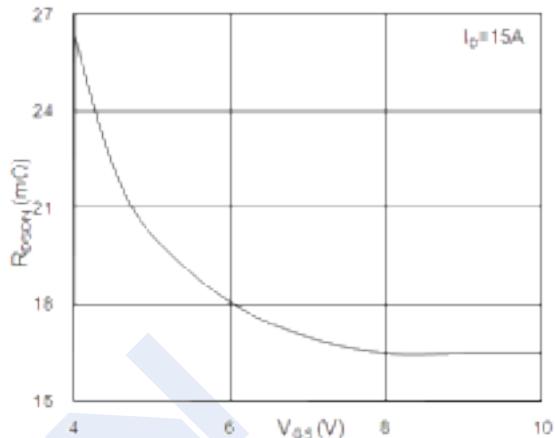


Fig.2 On-Resistance vs. Gate-Source

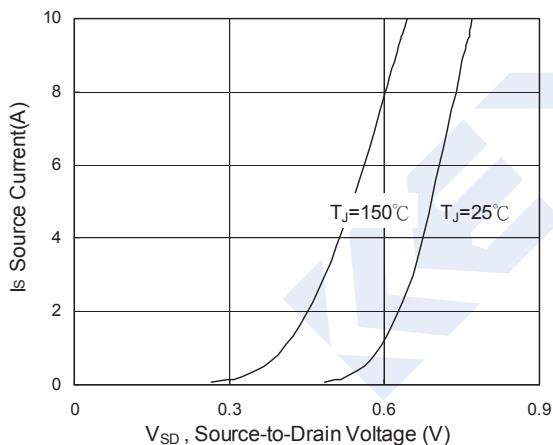


Fig.3 Forward Characteristics Of Reverse

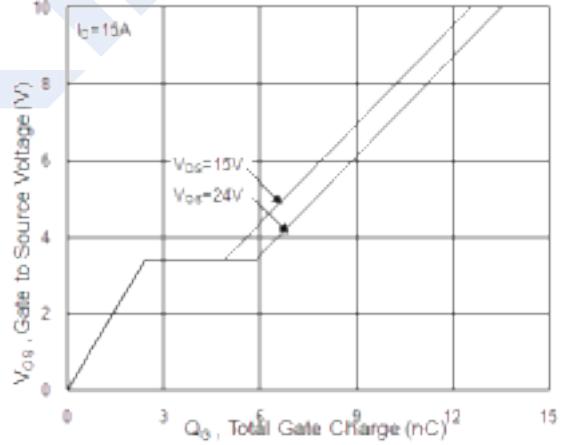
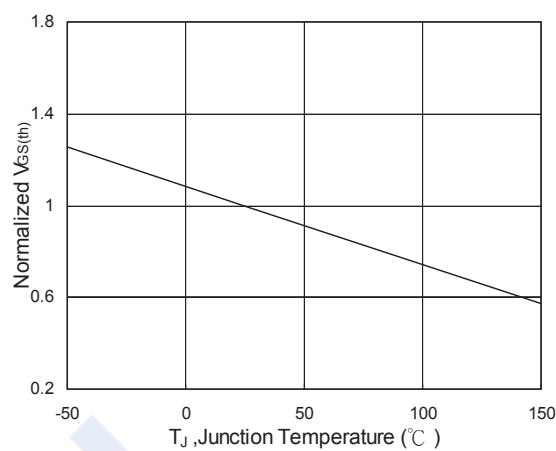
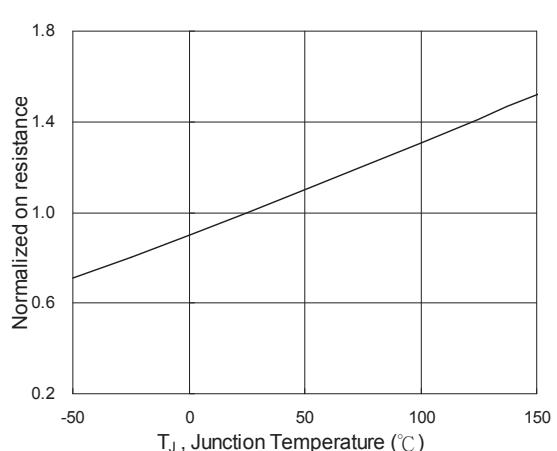
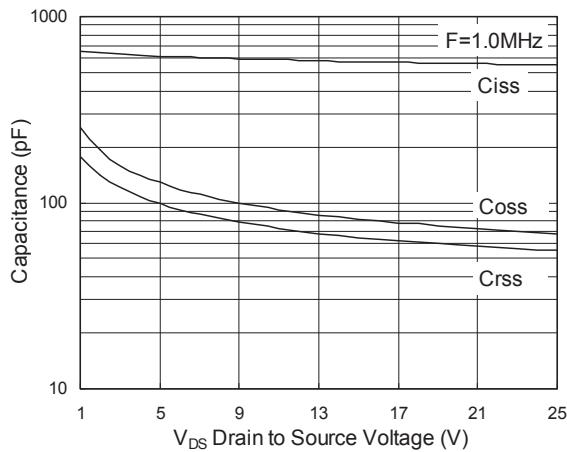
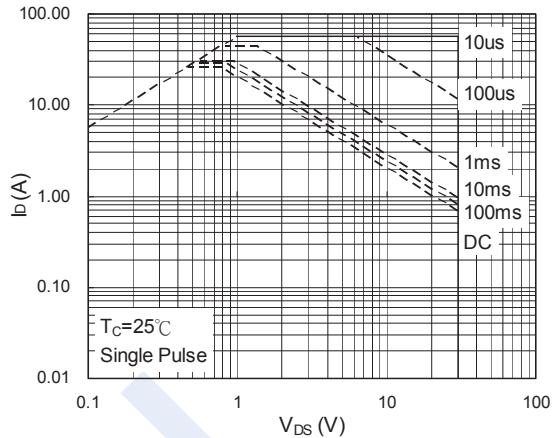
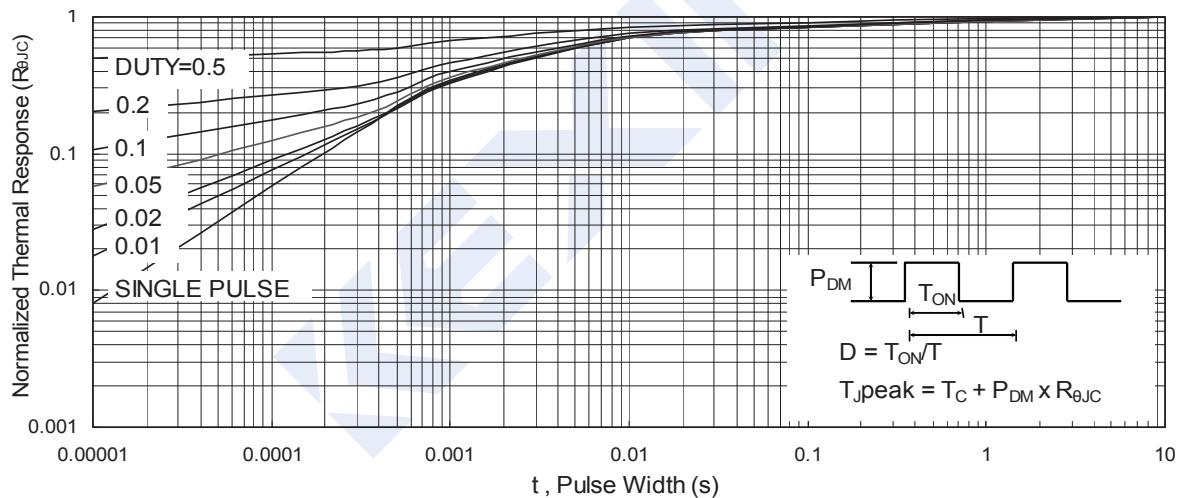
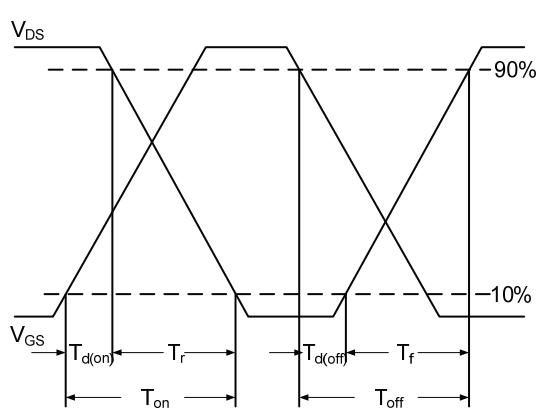
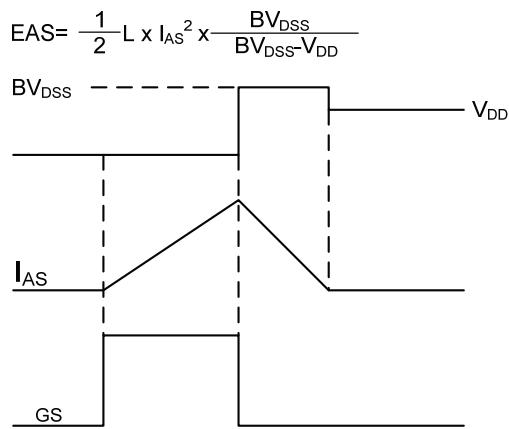


Fig.4 Gate-Charge Characteristics

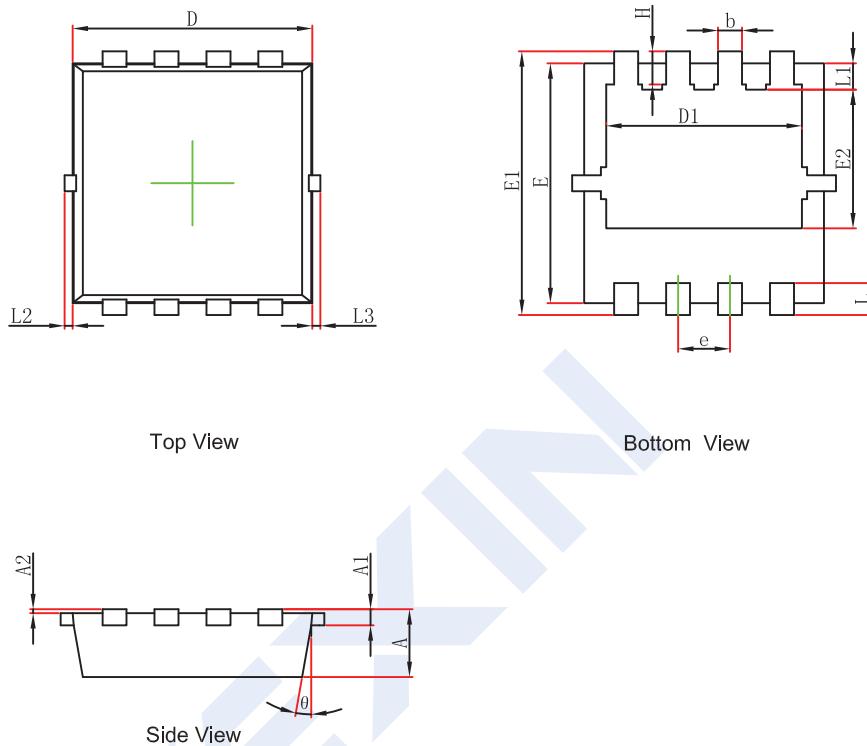
Fig.5 Normalized $V_{GS(th)}$ vs. T_J Fig.6 Normalized $R_{DS(on)}$ vs. T_J

N-Channel MOSFET**KI30N03DFN****Fig.7 Capacitance****Fig.8 Safe Operating Area****Fig.9 Normalized Maximum Transient Thermal Impedance****Fig.10 Switching Time Waveform****Fig.11 Unclamped Inductive Switching Waveform**

N-Channel MOSFET

KI30N03DFN

■ DFN3.3x3.3-8 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	2.300	2.600	0.091	0.102
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°